

### DESCRIPTION

The S1ZB60 is available in TO-269AA package.

# ORDERING INFORMATION

| Package Type                             | Part Number        |  |  |
|--|--------------------|--|--|
| TO-269AA                                 | S1ZB60             |  |  |
| Note                                     | SPQ: 3,000pcs/Reel |  |  |
| AiT provides all RoHS Compliant Products |                    |  |  |

# FEATURES

- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- This series is UL recognized under Component Index, file number E54214
- Glass passivated chip junctions
- High surge overload rating: 35A peak
- Saves space on printed circuit boards
- High temperature soldering guaranteed: 260°C/10 seconds at 5 lbs. (2.3kg) tension
- Available in TO-269AA package

#### MECHANICAL DATA

Case: Molded plastic body over passivated junctions Terminals: Plated leads solderable per MIL-STD-750, Method 2026 Polarity: Polarity symbols marked on body Mounting Position: Any Weight: 0.0078 ounce, 0.22 gram



### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

| Parameter Symbol                                      |                             | Symbol           | Value       | Unit               |
|---|-----------------------------|------------------|-------------|--------------------|
| Maximum Repetitive Peak Reverse Voltage               |                             | V <sub>RRM</sub> | 600         | V                  |
| Maximum RMS Voltage                                   |                             | V <sub>RMS</sub> | 420         | V                  |
| Maximum DC blocking voltage                           |                             | V <sub>DC</sub>  | 600         | V                  |
| Maximum Average Forward Rectified Curre               | ent At T <sub>A</sub> =30°C |                  |             |                    |
| On Glass-Epoxy P.C.B NOTE1                            |                             |                  | 0.5         | А                  |
| On Aluminum Substrate NOTE2                           |                             | 0.8              |             |                    |
| Peak Forward Surge Current 8.3ms Single               | Half                        |                  |             |                    |
| Sine-Wave Superimposed On Rated Load                  |                             | I <sub>FSM</sub> | 35.0        | А                  |
| (JEDEC Method)  |                             |                  |             |                    |
| Rating for Fusing (t<8.3ms)                           |                             | l²t              | 5.0         | A <sup>2</sup> sec |
| Maximum Instantaneous Forward Voltage Drop            |                             | VF               | 1.0         |                    |
| Per Leg at 0.4A                                       |                             |                  |             | V                  |
| Maximum DC Reverse Current at Rated                   | T <sub>A</sub> =25°C        | IR               | 5.0         | uA                 |
| DC Blocking Voltage Per Leg                           | T <sub>A</sub> =125°C       |                  | 100         |                    |
| Typical Junction Capacitance Per Leg <sup>NOTE3</sup> |                             | CJ               | 13.0        | pF                 |
| Typical Thermal Resistance Per Leg                    | NOTE1                       | Reja             | 85.0        | °C/W               |
|   | NOTE2                       | Reja             | 70.0        |                    |
|   | NOTE1                       | R <sub>θJL</sub> | 20.0        |                    |
| Operating Junction and Storage Temperature Range      |                             | Tj, Tstg         | –55 to +150 | °C                 |

Ratings at 25°C ambient temperature unless otherwise specified.

Stresses above may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the Electrical Characteristics are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

NOTE1: On glass epoxy P.C.B. mounted on 0.05 x 0.05" (1.3 x 1.3mm) pads

NOTE2: On aluminum substrate P.C.B. with an area of 0.8" x 0.8" (20 x 20mm) mounted on 0.05 x 0.05"(1.3 x 1.3mm) solder pad NOTE3: Measured at 1.0 MHz and applied reverse voltage of 4.0 Volts



#### TYPICAL CHARACTERISTICS

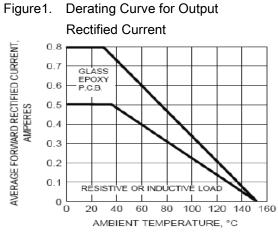
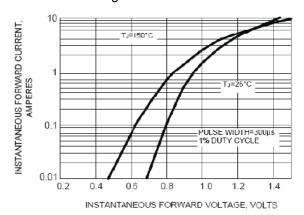
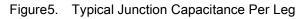


Figure 3. Typical Forward Voltage Characteristics Per Leg





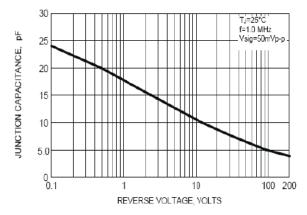


Figure 2. Maximum Non-Repetitive Peak Forward

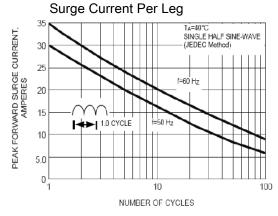
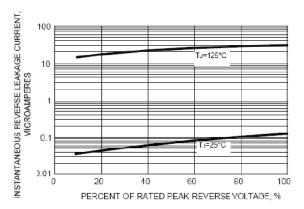


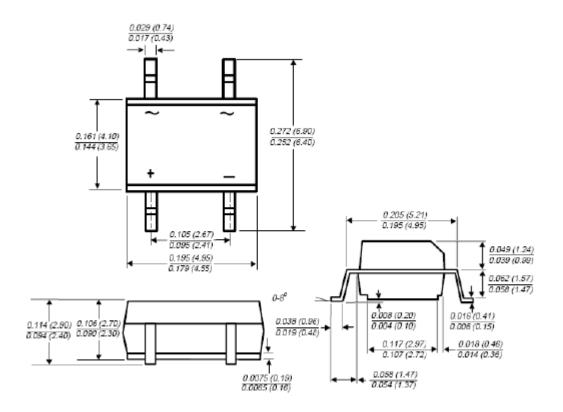
Figure 4. Typical Reverse Leakage Characteristics Per Leg





# PACKAGE INFORMATION

Dimension in TO-269AA Package (Unit: mm)





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